



Material Content Data Sheet



Sales Product Name		2EDL05N06PF		Issued		20. May 2016		
MA#		MA001371652						
Package		PG-DSO-8-53		Weight*		80.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	1.19	1.19	11864	11864
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.034	0.04		419	
	non noble metal	iron	7439-89-6	0.673	0.84		8387	
wire	non noble metal	copper	7440-50-8	27.330	34.05	34.94	340529	349440
	noble metal	gold	7440-57-5	0.185	0.23	0.23	2305	2305
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1237
plastics		epoxy resin	-	5.359	6.68		66771	
	inorganic material	silicondioxide	60676-86-0	44.162	55.02	61.82	550246	618254
leadfinish	non noble metal	tin	7440-31-5	0.824	1.03	1.03	10267	10267
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1116	1116
glue	plastics	acrylic resin	-	0.119	0.15		1486	
	noble metal	silver	7440-22-4	0.423	0.53	0.68	5268	6754
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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